**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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| Applicant(s): AKAMATSU et al. | Atty. Dkt.: 01-065-DIV |
| Serial No.: Unknown | Group Art Unit: |
| Filed: Concurrently herewith | Examiner: |
| Title: ELECTRICAL WIRING OF SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE | |

Commissioner for Patents
Arlington, VA 22202

Date: September 9, 2003

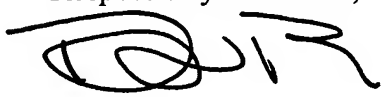
## INFORMATION DISCLOSURE STATEMENT

Sir:

Pursuant to 37 C.F.R. §1.56, the reference(s) listed on the attached Form PTO-1449 is/are being submitted for consideration by the Examiner without any admission that it/they constitute(s) statutory prior art, or without any admission that it/they contain(s) subject matter that anticipates the invention or renders the invention obvious to a person of ordinary skill in the art.

The Examiner is requested to initial the attached PTO Form-1449 and to return a copy of same to the undersigned attorney as proof that the listed reference(s) has/have been considered and made of record.

Respectfully submitted,



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| FORM PTO-1449 | ATTY. DKT NO. 01-065-DIV | SER. NO. |
|---|---|---|
| | APPLICANT **AKAMATSU et al.** | |
| | FILING DATE September 09, 2003 | GROUP |

**REFERENCE DESIGNATION**

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| | | 10-98041 | 4/98 | JAPAN | | | | X | |
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| | | 0525637 | 2/93 | EPO | | | | | |
| | | 3-3395 | 1/91 | JAPAN | | | | X | |
| | | JP6-163877 | 6/94 | JAPAN | | | | X | |

**OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)**

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| EXAMINER | | DATE CONSIDERED |

Rev. 10/94 (Form 3.05)

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